semiconductor packaging news



We search for industry news, so you don't need to.

2027 Media Guide



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News Focused on Semiconductor Packaging

Ultra-Thin Wafer Handling
Brewer Science temporary wafer bonding systems allow for safe handling and transport of ultrathin wafers during rigorous backside processing steps.
Brewer Science

Sponsor

Global Silicon Wafer Shipments to Rebound 5.4% in 2025
Global silicon wafer shipments will rise 5.4% in 2025 to 12,824 million square inches, SEMI reported, driven by AI-fueled demand for advanced wafers. Growth will continue through 2028, reaching a record 15,485 MSI as AI computing expands from data centers to the edge.
SEMI

Tough Engineering Changes? Where Can You Turn?
Engineering changes are a reality that need to be dealt with. Do you have qualified rework technicians to do the job efficiently and reliably?
Circuit Technology Center

Sponsor

Jensen Huang says Nvidia's AI chips are now being manufactured in Arizona
Nvidia CEO Jensen Huang said its Blackwell AI chips are now fully produced and assembled in Arizona after Trump urged U.S. manufacturing. At GTC, Nvidia also unveiled a $1B Nokia partnership for 5G/6G tech and new quantum computing projects to bolster U.S. innovation.
CNBC

Multi-Sensor Metrology for the most challenging Advanced Packaging Applications
Users want to measure various applications on one tool rather than several tools to get the required results. Ultra-precise, non-contact measuring techniques work for a multitude of packaging applications
Technical Paper

Discover consistency for your operations
Explore the reliable solutions for jet dispensing, conformal coating, plasma treatment, and selective soldering from Nordson.
Nordson Electronics Solutions

Sponsor

NVIDIA May Be TSMC's Only A16 Customer So Far While Apple Reportedly Yet to Start Talks
NVIDIA marked the first U.S.-made Blackwell wafer at TSMC's fab, signaling deeper ties as it becomes the sole customer testing TSMC's A16 node for 2027. The move marks AI's first lead in adopting TSMC's top process, though rising A16 costs could pressure NVIDIA's margins.
TrendForce

Technical Papers

- Novel Molded FCBGA Package Platform For Highly Reliable Automotive Applications
- Eliminating Interfacial Delamination in High-Power Automotive Devices
- RAIG Minimizes Corrosion, Allows Higher Gold on ENEPIG
- A Universal AI-Powered Segmentation Model for PCBA & Semiconductor
- Peer viewpoint: semiconductor innovation for telecommunication networks
- Current Characterization of Various Cu RDL Designs In Wafer Level Packages (WLP)
- Peer viewpoint: AI data centers are driving a semiconductor revolution

MORE TECH PAPERS

Fusion and Hybrid Bonding Experts
EVG's industry-leading process solutions, expertise and HI Competence Center accelerate the development and implementation of heterogeneous integration technology.
EV Group

Sponsor

Shanghai's IC Industry in High Gear, Up 11.3% in the First Three Quarters of 2025
Shanghai's GDP rose 5.5% year-on-year to CNY 4.07 trillion in the first three quarters of 2025, driven by strong growth in integrated circuits, biomedicine, and AI. IC output surged 11.3%, fueled by robust policies, investment funds, and a thriving tech ecosystem of 1,200+ firms.
TrendForce

Intel Reportedly Eyes Retired TSMC Veteran Wei-Jen Lo, Advanced Node Pioneer, to Lead R&D
Intel is reportedly courting retired TSMC veteran Wei-Jen Lo, a key figure behind TSMC's 2nm and EUV breakthroughs, to lead its R&D push in the sub-2nm race. The move, if confirmed, could shake Taiwan's chip sector as Intel expands its foundry business with U.S. backing.
TrendForce

Analysis Of Multi-Chiplet Package Designs and Requirements
This white paper discusses the rising complexity of multi-die semiconductor packages, challenges in testing interconnected chips, and how standards like UCIe simplify production testing workflows.
Amkor Technology

Sponsor

Today's Sponsor

brewer science

Die-Module Attach (Pastes & Films)
Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption- stress-free bonding.
AI Technology, Inc.

Sponsor

Test Your Knowledge
Which of the following was not invented by Thomas Edison? Light Bulb, Movie Projector, Telegraph or Phonograph.
See answer below.

EZ-FLO High Precision Dispense Tips
Each needle is machined from solid stainless steel as opposed to rolled tubing. The resulting smoother internal profile enhances material flow and consistency. Learn more.
DL Technology

Sponsor

Industry Press

Koh Young Unveils Breakthrough Innovations at Productronica and SEMICON Europa 2025
Koh Young will showcase a wave of innovations at Productronica and SEMICON Europa 2025, taking place November 18–21 at Messe München, Germany. Visitors can explore ...
Koh Young

ElevATE Expands Global Presence with New Office in Hsinchu, Taiwan
Semiconductor is excited to announce the opening of its first office in Hsinchu, Taiwan. The new location will strengthen support for customers and partners across Asia ...
ElevATE Semiconductor

STMicroelectronics' integrated GaN flyback converters simplify design and silence audible noise
STMicroelectronics is introducing a series of GaN flyback converters that simplify designing and building compact, efficient USB-PD chargers, fast battery chargers, and auxiliary ...
STMicroelectronics

Russelectric Highlights System Control Upgrades for Critical Power Equipment
Russelectric highlights its system control upgrades for critical power equipment for enhanced reliability, operational control, and ease-of-maintenance. These upgrades are ...
Russelectric

MORE INDUSTRY PRESS

Sponsor

"Build Up" I/C Packages -- USA Fabrication
High layer counts. Low CTE material sets. 20µm Dielectrics /12µm Traces - ITAR Approved - 50um "Stay Flat" Cores. Learn more.
Advanced Component Labs, Inc.

ACL

Quote of the Day

- 30,000+ daily e-mail subscribers
- 125,000 unique visitors past 12 months
- Readership from 130 countries
- #1 newsletter and website for industry professionals

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Why Advertise With Semiconductor Packaging News?

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Digital media continues to expand as industry professionals seek daily updates on news and events shaping the semiconductor packaging and micro-electronics market. An advertising campaign in Semiconductor Packaging News provides excellent visibility with high-frequency advertising designed to meet every budget. We reach 125,000 industry professionals who are eager to learn more about your products and services.

A digital advertising campaign features:

- Advertising campaigns in the daily newsletter & website
- Banner ads for branding (160 x 300 pixels vertical)
- Text ads intrigue readers to click to your web pages to learn more
- Technical papers provide lead generation for your sales channel
- Corporate news releases published at no cost
- Calendar to post your shows, webcasts and important events
- Custom e-mail broadcast to subscribers dedicated to your company

Analytical Data

Analytical data collected from independent firms confirm our readership continues to expand. Semiconductor Packaging News e-mail newsletter is broadcast to over 30,000 subscribers every business day.

During the past 12 months Semiconductor Packaging News has reached over 125,000 unique visitors from 130 countries. The e-mail newsletter subscriber base is always up-to-date and is managed by an independent e-mail company.

Top 10 markets by geographic readership:

- North America
- Japan
- South Korea
- Taiwan
- Singapore
- China
- Germany
- Netherlands
- United Kingdom
- France

Demographics by region of the world:
43% Americas, 35% Asia Pacific, and 22% Europe

Industry organizations such as SEMI, IMAPS, MEPTEC and IEEE partner with Semiconductor Packaging News to reach their members and drive visitors to their events and trade shows.

Comments from several Semiconductor Packaging News advertisers:

"SPN provides a great opportunity to reach a range of prospects on a daily basis for a very competitive price. We can advertise for an entire year for the cost of a small booth at a local show."
J.B.

"The White Paper program in SPN has delivered hundreds of prospects from around the world. This is a great way to reach new customers."
R.H.

"We are very pleased with the exposure and support from our ad campaign in SPN."
D.P.

"Semiconductor Packaging allows us to reach our markets around the globe. We book new orders from readers of SPN."
J.F.

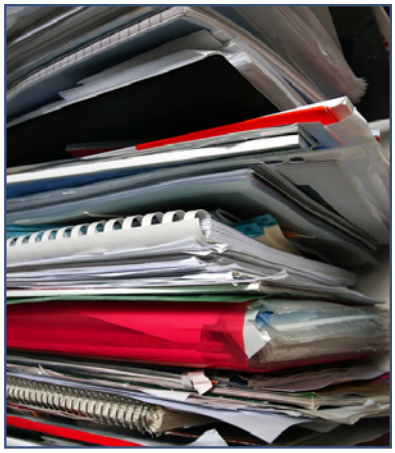
"In this period of decline in print publications, our customers are turning to the web as the source of information. We have benefited from our aggressive use of SPN as an advertising vehicle."
R.B.

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Semiconductor Packaging News Readers

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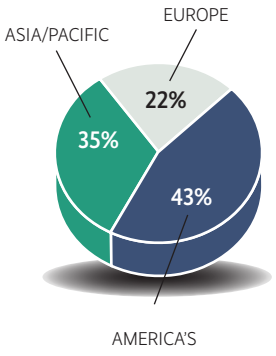


Over 30,000 daily subscribers find Semiconductor Packaging News to be their go-to source for news and information in the semiconductor and micro-electronics assembly market. Semiconductor Packaging News subscribers and website visitors are the industry professionals you want to reach; they are your prospects and your customers.

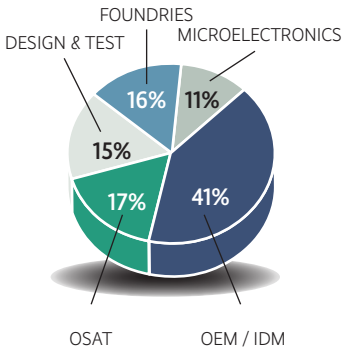
Rather than waiting for an issue of a trade publication every month or two, our daily e-mail broadcast reaches professionals that have a need to know – and who bear the responsibility for looking ahead to keep their companies on top! They keep themselves up to speed by reading Semiconductor Packaging News daily. Over 500,000 articles have been clicked and read by Semiconductor Packaging News readers.

Based on a readership survey we are proud to share data and commentary from industry professionals who took part in our survey.

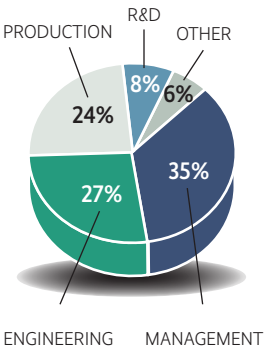
Readership Breakdown



Company Type



Job Description



Comments from several Semiconductor Packaging News subscribers:

"SPN is the best daily newsletter, I look forward to reading each day."

"I read SPN regularly and find the mix of information to be quite interesting."

"All the important news in one place, great way to start my morning."

"Semiconductor Packaging News is the only daily newsletter focused on the packaging side of the industry."

"This is the best daily newsletter for insight on the micro-electronics and semiconductor industries."

"As an Asia Pacific reader, I find your newsletter useful to gain the global perspective on the growing 3D packaging."

"Nice Job. Really stands out. Very newsy with lots of good stuff."

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Advertising Opportunities

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Semiconductor Packaging News advertising delivers results. We deliver your message to a targeted readership with the highest frequency. Advertising campaigns in Semiconductor Packaging News provide more visibility compared to other weekly newsletters and print media. The more often your ads run, the more response you will receive.

Banner Ads

Banner Ads are ideal for branding with corporate colors and a company logo. Large banner ads (160 x 300 pixels) provide significant space to deliver your messages for maximum exposure.

Text Ads

A well written text ad will intrigue the reader to click the ad to learn more about your product or service. The goal of a text ad is to deliver readers directly to your website. We encourage advertisers to run multiple text ads in their ad campaign at no extra cost.

Top Sponsor Position

Gold and silver-plus sponsors will have a "text ad" at the top of the newsletter and website once each month. Today's Sponsor includes the company's logo on the same day as the text on the top right column. Gold and silver-plus advertisers also receive premium positions each month.

Technical Papers generate leads each month

Semiconductor Packaging News publishes relevant technical papers at no cost allowing readers to download them with a simple registration. We collect names, company and e-mail addresses and provide to our advertisers at no additional cost.

Custom E-mail Broadcast

Broadcast a custom e-mail to our subscribers to showcase new products, promote a webinar, conference or award. The custom e-mail broadcast is focused exclusively on your company and can be reserved for any day you want to share the news with our readers. Ask us for more details.

Monthly Media Reports

Semiconductor Packaging News provides a monthly media report capturing data from your campaign including banner ad and text ad clicks. We also provide a list of readers who download your published technical papers to share with your sales channel.


Media Report

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EV Group

2025 Ad Performance

Your Available Ads

Did You Know: Text ads will typically deliver 2-3 times as many clicks as a banner ad. Advertisers use banner ads to build the company brand and text ads to intrigue readers to click on their ads and drive readers to pages on their website.

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Rate Card



Premium Positions

Text Ad

Vertical Banner Ads

Sponsor Text Ad

Sponsor Logo

Premium Position

Text Ad

Text Ad

Silver Campaign

The Silver Campaign includes 8 days per month in the e-mail newsletter and website. Ads will usually run twice per week in this campaign.

3-month campaign $1,200month
6-month campaign $1,100/month
12-month campaign $1000/month

Silver-Plus Campaign

The Silver-Plus Campaign includes 10 days per month in the e-mail newsletter and website plus a premium ad position each month.

3-month campaign $1,500/month
6-month campaign $1,450/month
12-month campaign $1,350/month

Gold Campaign

The Gold Campaign includes 15 days per month in the e-mail newsletter and website including a top sponsor position with company logo each month plus a premium position each month.

3-month campaign $2,000/month
6-month campaign $1900/month
12-month campaign $1800/month

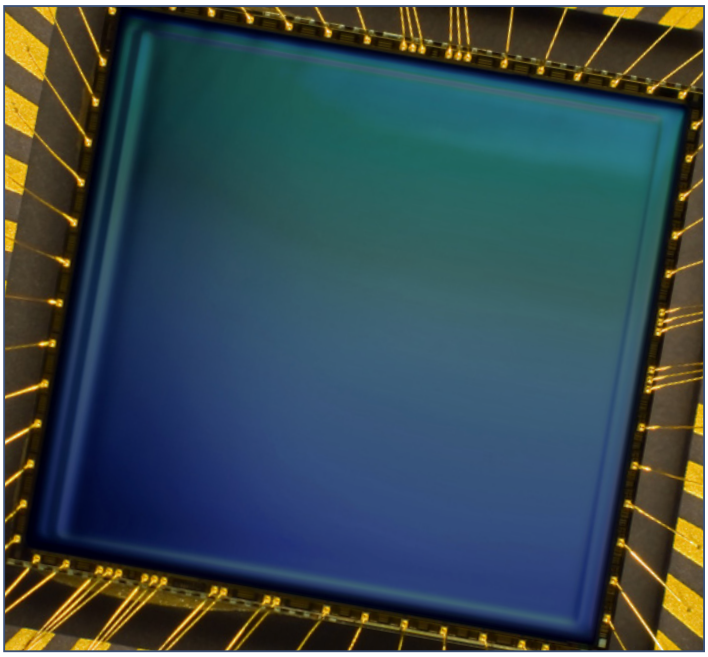
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About Us

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We believe it's our job to dig through the unending stream of news, articles, features, and discussions to deliver information, covering the world of semiconductor packaging and micro electronics, to our readers. Every night we scour the news from over 100 sources to find the best industry news articles. We package this information into a convenient newsletter that is delivered to our subscribers e-mail every business day.



The Semiconductor Packaging Newsletter and website features links to industry and technology news stories and feature articles about the semiconductor packaging market. We publish the latest corporate and product news announcements industry companies submit to us.

Thousands of technical papers are downloaded every month and we'll publish your technical paper at no cost. You'll also find commentaries, cartoons, an industry event calendar and much more.

We look forward to working with you on your digital sponsorship campaign.



Jeff Ferry
Publisher
jferry@circuitnet.com
Phone: 843.682.4755



Ken Cavallaro
Editor & Business Manager
kcavallaro@circuitnet.com
Phone: 978.505.1032



Lynne Schueler
Administration
lschueler@circuitnet.com
Phone: 978.887.3469

Circuitnet Media LLC, 58 Plaistow Road Ste, A15 #1013 Plaistow, NH 03865